



Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

* : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-12-04
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Floriana SAN BIAGIO	Representative Title	AMS MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement	
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Legal Statement	
Supplier Acceptance *	true
	Legal Declaration * Standard
Legal Statement	Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	A98CUF36AJ6	A	MU1A	2018-12-04
	Amount	UoM	Unit type	ST ECOPACK Grade
	1930	mg	Each	ECOPACK® 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	245	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
DSO	15.9X11X3.5	36	gull wing	
Comment	PowerSO 36 .430 BODY WIDTH; MDF valid for L6206PD and L6206PD013TR			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	8.95	Solder	4637

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	A98CUF36AJ6				6000001.0	999999.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	14.750	mg	supplier	die	Silicon (Si)	7440-21-3		14.193	mg	962237	7355
				supplier	metallization	Aluminium (Al)	7429-90-5		0.108	mg	7322	56
				supplier	metallization	Copper (Cu)	7440-50-8		0.002	mg	136	1
				supplier	metallization	Titanium (Ti)	7440-32-6		0.012	mg	814	6
				supplier	Passivation	Silicon Nitride	12033-89-5		0.032	mg	2169	17
				supplier	Passivation	Silicon Oxide	7631-86-9		0.185	mg	12542	96
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.008	mg	542	4
				supplier	back side metallization	Gold (Au)	7440-57-5		0.022	mg	1492	11
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.072	mg	4881	37
				supplier	polymer die coating	PIXI Gamma-butyrolactone	96-48-0		0.116	mg	7864	60
				Leadframe	M-004 Copper and its alloys	1234.872	mg	supplier	alloy	Copper (Cu)	7440-50-8	
supplier	alloy	Iron (Fe)	7439-89-6						0.568	mg	460	294
supplier	alloy	Iron Phosphide (FeP)	26508-33-8						1.037	mg	840	537
supplier	metallization	Silver (Ag)	7440-22-4						0.302	mg	245	157
supplier	solder	Lead (Pb)	7439-92-1					7a-Lead in high me	8.948	mg	974940	4637
Soft solder	Solder	9.178	mg	supplier	solder	Silver (Ag)	7440-22-4		0.138	mg	15036	72
				supplier	solder	Tin (Sn)	7440-31-5		0.092	mg	10024	48
Bonding wires	M-011 Other inorganic materials	1.142	mg	supplier	wire	Copper (Cu)	7440-50-8		1.142	mg	1000000	592
Encapsulation	M-015 Other organic materials	663.782	mg	supplier	mold compound	silica vitreous	60676-86-0		587.447	mg	885000	304429
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		35.180	mg	52999	18231
				supplier	mold compound	Phenol Resin	205830-20-2		26.551	mg	40000	13759
				supplier	mold compound	epoxy resin	Proprietary		13.276	mg	20001	6880
connections coating	Solder	5.946	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		5.946	mg	1000000	3081